

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	171179	"438"/\$.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 19:54
L2	79926	(microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:06
L3	3171	(microelectronic or micro-electronic) and (protrusion\$1 or solder\$1 or bump\$1 or bump\$1 or post\$1) and (assembl\$3) and (remov\$3 or etch\$3 or pattern\$3).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:05
L4	878	(microelectronic or micro-electronic) and (protrusion\$1 or solder\$1 or bump\$1 or bump\$1 or post\$1) and (assembl\$3) and ((remov\$3 or etch\$3 or pattern\$3) near5 (surface)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 19:57
L5	3815	(microelectronic or micro-electronic) and (protrusion\$1 or solder\$1 or bump\$1 or bump\$1 or post\$1) and (assembl\$3) and ((remov\$3 or etch\$3 or pattern\$3) near5 (surface))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 19:58
L6	501	5 and ((microelectronic or micro-electronic) near15 (protrusions or bumps or solders or posts))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 19:59
L7	233	6 and (remov\$3) near15 (protrusions or bumps or solders or posts)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 20:39
L8	121	7 and (assembl\$3) near15 (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:04
L9	29	1 and 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 20:39

L10	186	6 and (remov\$3) near5 (protrusions or bumps or solders or posts)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:07
L11	101	10 and (assembl\$3) near15 (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:07
L12	24	1 and 11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:17
L13	53	7 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:04
L14	34	13 and (assembl\$3) with (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:04
L15	27	13 and (assembl\$3) near10 (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:04
L16	2	(protrusion\$1 or solder\$1 or bump\$1 or bump\$1 or post\$1) with (poject\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:06
L17	51709	(protrusion\$1 or solder\$1 or bump\$1 or bump\$1 or post\$1) with (project\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:06
L18	35623	(protrusion\$1 or solder\$1 or bump\$1 or bump\$1 or post\$1) near5 (project\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:06
L19	377	2 and 18	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:06

L20	105	19 and (remov\$3) near5 (protrusions or bumps or solders or posts)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:07
L21	41	20 and (assembl\$3) near15 (microelectronic or micro-electronic)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:07
L22	4335	(protrusion) near5 (project)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:21
L23	14	2 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:21
L24	1	(protrusion) near15 (project near15 meters)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:21
L25	5420	(protrusion) near15 (project)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:22
L26	15	2 and 25	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:22
L27	1991	(solder) near15 (project)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:22
L28	95	2 and 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:22
L29	22	1 and 28	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/29 21:22